

| External_Type   | Material_Group   | Substances   | CAS_Number | Mass         | Mass_Percentage_in_Leaf | Massmg         |
|-----------------|------------------|--|------------|--------------|-------------------------|----------------|
| Die             | Metal oxide      | Lead Dioxide (PbO2)                                    | 1309-60-0  | 0            | 0.97                    | 0.04           |
|                 | Doped silicon    | Silicon (Si)   | 7440-21-3  | 0.24         | 99.03                   | 3.66           |
| <b>Subtotal</b> |                  |  |            | <b>0.24</b>  | <b>100</b>              | <b>3.7</b>     |
| Solder Wire     | Tin alloy        | Tin (Sn)   | 7440-31-5  | 0.02         | 10.0                    | 0.24           |
|                 | Silver alloy     | Silver (Ag)  | 7440-22-4  | 0            | 2.0                     | 0.05           |
|                 | Lead alloy       | Lead (Pb)  | 7439-92-1  | 0.14         | 88.0                    | 2.11           |
| <b>Subtotal</b> |                  |  |            | <b>0.16</b>  | <b>100</b>              | <b>2.4</b>     |
| Wire            | Pure metal       | Aluminium (Al)   | 7429-90-5  | 0.28         | 100.0                   | 4.21           |
|                 | <b>Subtotal</b>  |  |            |              | <b>0.28</b>             | <b>100</b>     |
| Post-plating    | Pure metal       | Tin (Sn)   | 7440-31-5  | 0.34         | 100.0                   | 5.17           |
|                 | <b>Subtotal</b>  |  |            |              | <b>0.34</b>             | <b>100</b>     |
| Lead Frame      | Copper alloy     | Phosphorous (P)  | 7723-14-0  | 0.01         | 0.03                    | 0.15           |
|                 | Pure metal layer | Zinc (Zn)  | 7440-66-6  | 0.01         | 0.02                    | 0.1            |
|                 | Pure metal layer | Tin (Sn)   | 7440-31-5  | 0.01         | 0.03                    | 0.15           |
|                 | Pure metal layer | Iron (Fe)  | 7439-89-6  | 0.04         | 0.11                    | 0.54           |
|                 | Pure metal layer | Copper (Cu)  | 7440-50-8  | 32.51        | 99.81                   | 488.86         |
| <b>Subtotal</b> |                  |  |            | <b>32.58</b> | <b>100</b>              | <b>489.8</b>   |
| Mould Compound  | Polymer          | Phenol Formaldehyde resin (generic)                    | 9003-35-4  | 3.32         | 5.0                     | 49.92          |
|                 | Polymer          | Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) | 25928-94-3 | 9.96         | 15.0                    | 149.77         |
|                 | Filler           | Silica fused   | 60676-86-0 | 2.99         | 4.5                     | 44.93          |
|                 | Carbon Black     | Carbon black   | 1333-86-4  | 0.33         | 0.5                     | 4.99           |
|                 | Filler           | Misc. Silica compounds (generic)                       | 14808-60-7 | 49.8         | 75.0                    | 748.83         |
| <b>Subtotal</b> |                  |  |            | <b>66.4</b>  | <b>100</b>              | <b>998.44</b>  |
| <b>Total</b>    |                  |  |            | <b>100</b>   | <b>100</b>              | <b>1503.72</b> |

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